## Compact housing for BI-SKAP with MPL

Part no. IKT-BI-3854/SKAP/MP

Catalog No. 147524

Alternate Catalog IKT-BI-3854-SKAP-MP

No.

**EL-Nummer** 1728082

(Norway)



## Design verification as per IEC/EN 61439

| Heat dissipation, at an ambient temperature of 35°C, delta T: 20 degrees in top of the enclosure, calculated as per IEC 60890  Individual enclosure for wall mounting  Pv W 38  Starting enclosure for wall mounting  Pv W 36  Middle enclosure for wall mounting  Pv W 33  Heat dissipation, at an ambient temperature of 35°C, delta T: 35 degrees in top of the enclosure, calculated as per IEC 60890  Individual enclosure for wall mounting  Pv W 77  Starting enclosure for wall mounting  Pv W 72  Middle enclosure for wall mounting  Pv W 66   | boolgii vormoution do por 120/211 or 100                                   |         |   |  |
|--|--|---------|---|--|
| Individual enclosure for wall mounting Po W 3 Starting enclosure for wall mounting Po W W 3 Starting enclosure for wall mounting Po W W 3 Middle enclosure for wall mounting Po W W 3 Individual enclosure for wall mounting Po W W 7 Individual enclosure for wall mounting Po W W 7 Starting enclosure for wall mounting Po W W 7 Starting enclosure for wall mounting Po W W 7 Individual enclosure for wall mounting Po W W 7 Starting enclosure for wall mounting Po W W 7 Individual enclosure for wall enclosure for wall enclosure seal enclosure sea enclosure sea en | Technical data for design verification                                     |         |   |  |
| Starting enclosure for wall mounting  Middle enclosure for wall mounting  Py W 33  Head dissipation, at an ambitinet temperature of 35°C, data T. 35 degrees into port the enclosure, calculated as per LEC 68880  Individual enclosure for wall mounting  Py W 77  Starting enclosure for wall mounting  Py W 77  Middle enclosure for wall mounting  Py W 77  Middle enclosure for wall mounting  Py W 77  Middle enclosure for wall mounting  Py W 78  Meets the product standard's requirements.  102.2 Corrosion resistance  102.2 I Verification of thermal stability of enclosures  102.2 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects  102.2 Strength of a resistance of insulating materials to abnormal heat and fire due to internal electric effects  102.2 I Issertiction of resistance of insulating materials to abnormal heat and fire due to internal electric effects  102.2 I Issertiction of several conditions of the strength of the product standard's requirements.  Moets the product standard's requirements.  Moets the product standard's requirements.  Moets the product standard's requirements.  Not relevant to indoor installations.  102.2 Issertiction of ASSEMBUES  102.2 I Issertiction of ASSEMBUES  103.0 Degree of protection of ASSEMBUES  104.0 Clearances and crepage distances  105.0 Protection against electric shock  106.1 Corroscition of ASSEMBUES  107.1 Internal electric circuits and connoctions  108.1 Is the panel builder's responsibility.  109.1 Insulation properties  109.2 Power-frequency electric strength  109.3 Insulation properties  109.3 Insulation properties  109.3 Insulation properties  109.3 Insulation properties  109.4 Restrang of enclosures made of insulating material  10.10 Temperature rise  10.10 Temperature rise  The panel builder's responsibility.  10.10 Temperature rise  10.10 Tempera |  |         |   |  |
| Middle enclosure for wall mounting  Heat dissipation, at an ambient temperature of 35°C, deta T. 35 degrees in two of the enclosure, calculated as per ICC 60000  But dissipation, at an ambient temperature of 35°C, deta T. 35 degrees in two of the enclosure, calculated as per ICC 60000  Starting enclosure for wall mounting  Py W 72  Middle enclosure for wall mounting Py W 72  Middle enclosure for wall mounting Py W 73  ECEN 1343 design verification  10.2.2 Strength of materials and parts  10.2.2 Strength of materials and parts  10.2.2 Strength of materials and parts  10.2.3 I Verification of thermal stability of enclosures  10.2.3 I Verification of resistance of insulating materials to normal heat and fire due to internal electric of feets  10.2.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric offects  10.2.4 Resistance to ultra-violet (UV) radiation  10.2.5 Uffing  10.2.5 Uffing  10.2.6 Mechanical impact  10.2.7 Inscriptions  10.3 Degree of protection of ASSEMBLIES  10.3 Degree of protection of ASSEMBLIES  10.3 Degree of protection of ASSEMBLIES  10.4 Clearances and creepage distances  10.5 Incorporation of switching devices and components  10.5 Incorporation of switching devices and components  10.6 Incorporation of switching devices and components  10.9 Insulation properties  10.9 Power-frequency electric strength  10.9 Supplies withstand voltage  10.9 Insulation groperties  10.9 Insula | Individual enclosure for wall mounting                                     | $P_{V}$ | W | 38   |
| Heat dissipation, at an ambient temperature of 35°C, delta T. 35 degrees in top of the enclosure, calculated as per EC 00800 Py W 77  Individual enclosure for wall mounting Py W 75  Starting enclosure for wall mounting Py W 75  Middle enclosure for wall mounting Py W 75  Middle enclosure for wall mounting Py W 75  ECFL 61439 design verification  10.2 Strength of materials and parts  10.2.2 Cerrosion resistance  10.2.3 Liverification of themal stability of enclosures  10.2.3 Liverification of fresistance of insulating materials to normal heat and fire due to internal electric effects  10.2.3 Liverification of resistance of insulating materials to shormal heat and fire due to internal electric effects  10.2.4 Resistance to ultra-violot (UV) radiation  10.2.5 Lifting  10.2.6 Mechanical impact  10.2.6 Mechanical impact  10.2.7 Internal protection of ASSEMBLES  10.3 Degree of protection of ASSEMBLES  10.4 Clearances and creepage distances  10.5 Protection against electric shock  10.6 Incorporation of switching devices and components  10.8 Incorporation of switching devices and components  10.8 Incorporation of switching devices and components  10.9 Installation properties  10.9 Installation p | Starting enclosure for wall mounting                                       | $P_V$   | W | 36   |
| Individual enclosure for wall mounting Pv W 72 Starting enclosure for wall mounting Pv W 72 Middle enclosure for wall mounting Pv W 75 Middle enclosure for wall mounting W 75 Meets the product standard's requirements.  Meets the product standard's requirements.  Most relevant to indoor installations.  Most relevant to indoor installations.  Not relevant to indoor installations.  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Meets the product standard's requirements.  IK08  Me | Middle enclosure for wall mounting   | $P_V$   | W | 33   |
| Starting enclosure for wall mounting Middle enclosure for wall mounting Py W 66  EC/EN 61439 design verification 10.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.3 I Verification of thermal stability of enclosures 10.2.3 Verification of thermal stability of enclosures 10.2.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2 Edecardor of protection of experiments 10.2.5 Lifting 10.2.5 Lifting 10.2.5 Lifting 10.2.7 Inscriptions 10.3.7 Inscriptions 10.3.8 Protection against electric shock 10.3.8 requirements 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.5 Protection against electric shock 10.5 Internal electric alcircuits and connections 10.9 Insulation properties 10.9 Insulation pr |  |         |   |  |
| Middle enclosure for well mounting  Py W 66  EC/EN 61439 design verification  10.2 Strength of meterials and parts  10.2.2 Corrosion resistance  10.2.3 Verification of thermal stability of enclosures  10.2.3 Verification of resistance of insulating materials to normal heat and fire due to internal electric effects  10.2.4 Resistance to ultra-violet (UV) radiation  10.2.5 Litting  10.2.6 Mechanical impact  10.2.7 Inscriptions  10.2.7 Inscriptions  10.2.8 Protection against electric shock  10.8 Protection against electric shock  10.8 Frotection against electric shock  10.8 Frotection against electric strength  10.9 Prover-frequency electric strength  10.9 Prover-frequency electric strength  10.9 Prover-frequency electric strength  10.9 Insulation properties  10.9 Prover-frequency electric strength  10.9 Prover-frequency electric strength  10.9 Insulation properties  10.9 Prover-frequency electric strength  10.9 Insulation properties  10.9 Insulation properties  10.9 Insulation properties  10.9 Insulation properties  10.9 Prover-frequency electric strength  10.9 Insulation properties  10.9 Prover-frequency electric strength  10.9 Insulation properties  10.9 Insulation properties  10.9 Insulation properties  10.9 Prover-frequency electric strength  10.9 Insulation properties  10.9 Insulation propertie | Individual enclosure for wall mounting                                     | $P_V$   | W | 77   |
| ECEN 61439 design verification  10.2 Strength of materials and parts  10.2.2 Corrosion resistance  10.2.3.1 Verification of thermal stability of enclosures  10.2.3.2 Verification of resistance of insulating materials to normal heat  10.2.3.3 Verification of resistance of insulating materials to normal heat  10.2.3.3.4 Verification of resistance of insulating materials to abnormal heat  10.2.3.3 Verification of resistance of insulating materials to abnormal heat  10.2.4 Resistance to ultra-violet (UV) radiation  10.2.5 Lifting  10.2.6 Machanical impact  10.2.7 Inscriptions  10.2.7 Inscriptions  10.2.8 Machanical impact  10.3.9 Opere of protection of ASSEMBLIES  10.4 Clearances and creepage distances  10.5 Protection against electric shock  10.5 Protection against electric shock  10.6 Incorporation of switching devices and components  10.8 Incorporation of switching devices and components  10.9 Insulation properties  10.9.2 Power-frequency electric strength  10.9.3 Insulation properties  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.10 Temperature rise  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  10.15 Lectromagnetic compatibility  10.16 Lectromagnetic compatibility  10.16 Lectromagnetic compatibility  10.17 Leteromagnetic compatibility  10.18 Lectromagnetic compatibility  10.19 Lectromagnetic compatibility  10.10 Lectromagnetic compatibility   | Starting enclosure for wall mounting                                       | $P_V$   | W | 72   |
| 10.2 Strength of materials and parts  10.2.2 Corrosion resistance  10.2.3.1 Verification of thermal stability of enclosures  Meets the product standard's requirements.  10.2.3.2 Verification of resistance of insulating materials to normal heat  10.2.3.3. Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects  10.2.4 Resistance to ultra-violet (UV) radiation  10.2.5 Lifting  10.2.6 Mechanical impact 10.2.7 Inscriptions  10.2.8 Mechanical impact 10.3. Degree of protection of ASSEMBLIES 10.3. Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.15 the panel builder's responsibility. 10.16 Incorporation of switchild devices and connections 10.10 Temperature rise 10.11 Short-circuit rating 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 10.15 the panel builder's responsibility.   | Middle enclosure for wall mounting   | $P_V$   | W | 66   |
| Meets the product standard's requirements.   10.2.3.1 Verification of thermal stability of enclosures   Meets the product standard's requirements.     10.2.3.2 Verification of resistance of insulating materials to normal heat and fire due to internal electric effects   Meets the product standard's requirements.     10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects   Meets the product standard's requirements.     10.2.4 Resistance to ultra-violet (UV) radiation   Not relevant to indoor installations.     10.2.5 Litting   Does not apply to enclosures without lifting aids.     10.2.5 Mechanical impact   IK08   IK08   IK08   IK08   IP30   IV30   IV   | IEC/EN 61439 design verification   |         |   |  |
| 10.2.3.1 Verification of thermal stability of enclosures   Meets the product standard's requirements.  | 10.2 Strength of materials and parts                                       |         |   |  |
| 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.3 Degree of protection of ASSEMBLIES 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Power-frequency electric strength 10.9.1 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.14 Stepanel builder's responsibility. 10.15 Internal electrical circuits and connections 10.16 Electromagnetic compatibility 10.17 Internal electrical circuits and connections 10.18 Connections for external conductors 10.19 Insulation properties 10.10 Temperature rise 10.10 Temperature rise 10.10 Temperature rise 10.10 Temperature rise calculation. Eaton will provide heat dissipation data for the devices.  | 10.2.2 Corrosion resistance  |         |   | Meets the product standard's requirements.                   |
| 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects  10.2.4 Resistance to ultra-violet (UV) radiation  10.2.5 Lifting  10.2.6 Mechanical impact  10.2.7 Inscriptions  10.2.9 Experiments  10.3 Degree of protection of ASSEMBLIES  10.4 Clearances and creepage distances  10.5 Protection against electric shock  10.5 Protection against electric shock  10.6 Incorporation of switching devices and components  10.7 Internal electrical circuits and connections  10.8 Connections for external conductors  10.9 Power-frequency electric strength  10.9.1 New even the panel builder's responsibility.  10.9 Power-frequency electric strength  10.9.2 Power-frequency electric strength  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  10.12 Electromagnetic compatibility  10.12 Electromagnetic compatibility  10.12 Electromagnetic compatibility  10.13 Short-circuit rating  10.14 Experiments.  Not relevant to indoor installations.  Not | 10.2.3.1 Verification of thermal stability of enclosures                   |         |   | Meets the product standard's requirements.                   |
| and fire due to internal electric effects  10.24 Resistance to ultra-violet (UV) radiation  10.25 Lifting  10.26 Mechanical impact  10.27 Inscriptions  10.30 Degree of protection of ASSEMBLIES  10.4 Clearances and creepage distances  10.5 Protection against electric shock  10.6 Incorporation of switching devices and components  10.7 Internal electrical circuits and connections  10.8 Connections for external conductors  10.9 Insulation properties  10.9 Power-frequency electric strength  10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  10.12 Electromagnetic compatibility  10.12 Electromagnetic compatibility  10.12 Electromagnetic compatibility  10.14 Electromagnetic compatibility  10.16 Incorporation of switching devices and components  10.17 Internal electrical circuits and connections  10.18 Legal Rule Add V AC  10.19 Insulation properties  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  10.14 Electromagnetic compatibility  | 10.2.3.2 Verification of resistance of insulating materials to normal heat |         |   | Meets the product standard's requirements.                   |
| 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.7 Inscriptions Meets the product standard's requirements. 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 11 Ikont-circuit rating 11 Ikont-circuit rating 12 Insulation properties 13 Insulation properties 14 In panel builder is responsibility. 15 In panel builder is responsibility. 16 In panel builder is responsibility. 17 In the panel builder is responsibility. 18 In panel builder is responsibility. 19 In the panel builder is responsibility. 19 In the panel builder is responsibility. 10 In the panel builder is responsibility.  |  |         |   | Meets the product standard's requirements.                   |
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| 10.2.7 Inscriptions  Meets the product standard's requirements.  10.3 Degree of protection of ASSEMBLIES  10.4 Clearances and creepage distances  10.5 Protection against electric shock  10.6 Incorporation of switching devices and components  10.7 Internal electrical circuits and connections  10.8 Connections for external conductors  10.9 Insulation properties  10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  Is the panel builder's responsibility.  Is the panel builder's responsibile for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.  Is the panel builder's responsibility.  Is the panel builder's responsibility.  | 10.2.5 Lifting   |         |   | Does not apply to enclosures without lifting aids.           |
| 10.3 Degree of protection of ASSEMBLIES  10.4 Clearances and creepage distances  10.5 Protection against electric shock  10.6 Incorporation of switching devices and components  10.7 Internal electrical circuits and connections  10.8 Connections for external conductors  10.9 Insulation properties  10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  Is the panel builder's responsibility.  Is the panel builder's responsibility.  Is the panel builder is responsibility.  Is the panel builder is responsibility on the temperature rise calculation. Eaton will provide heat dissipation data for the devices.  Is the panel builder's responsibility.  Is the panel builder's responsibility.  | 10.2.6 Mechanical impact   |         |   | IK08   |
| 10.4 Clearances and creepage distances  10.5 Protection against electric shock  20.1 0; meets the product standard's requirements.  10.6 Incorporation of switching devices and components  10.7 Internal electrical circuits and connections  10.8 Connections for external conductors  10.9 Insulation properties  10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  Is the panel builder's responsibility.  Is the panel builder's responsibility.  Is the panel builder's responsibility.  Is the panel builder is responsibility.  Is the panel builder is responsibility.  Is the panel builder's responsibility.   | 10.2.7 Inscriptions  |         |   | Meets the product standard's requirements.                   |
| 10.5 Protection against electric shock   < 0.1 Ω; meets the product standard's requirements.   | 10.3 Degree of protection of ASSEMBLIES                                    |         |   | IP30   |
| 10.6 Incorporation of switching devices and components  10.7 Internal electrical circuits and connections  10.8 Connections for external conductors  10.9 Insulation properties  10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  Is the panel builder's responsibility.   | 10.4 Clearances and creepage distances                                     |         |   | Is the panel builder's responsibility.                       |
| 10.7 Internal electrical circuits and connections  10.8 Connections for external conductors  10.9 Insulation properties  10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  Is the panel builder's responsibility.  Is the panel builder's responsibility.  Is the panel builder is responsibility.  Is the panel builder's responsibility.  Is the panel builder's responsibility.  | 10.5 Protection against electric shock                                     |         |   | $<$ 0.1 $\Omega;$ meets the product standard's requirements. |
| 10.8 Connections for external conductors  10.9 Insulation properties  10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  10.12 Electromagnetic compatibility  10.15 Insulation properties  Is the panel builder's responsibility.  Is the panel builder's responsibility.  | 10.6 Incorporation of switching devices and components                     |         |   | Is the panel builder's responsibility.                       |
| 10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  2.5 kV  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  Ui = 400 V AC  2.5 kV  Does not apply to metal enclosures.  The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  10.13 Short-circuit rating  10.14 Short-circuit rating  10.15 Short-circuit rating  10.16 Short-circuit rating  10.17 Short-circuit rating  10.18 Short-circuit rating  10.19 Short-circuit rating  10.10 Short-circuit rating   | 10.7 Internal electrical circuits and connections                          |         |   | Is the panel builder's responsibility.                       |
| 10.9.2 Power-frequency electric strength  10.9.3 Impulse withstand voltage  2.5 kV  10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  U <sub>i</sub> = 400 V AC  10.9 A C  10.9 A Testing of enclosures made of insulating material  Does not apply to metal enclosures.  The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  10.13 Short-circuit rating  10.14 Electromagnetic compatibility  | 10.8 Connections for external conductors                                   |         |   | Is the panel builder's responsibility.                       |
| 10.9.3 Impulse withstand voltage 2.5 kV 10.9.4 Testing of enclosures made of insulating material Does not apply to metal enclosures.  The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.  10.11 Short-circuit rating Is the panel builder's responsibility.  10.12 Electromagnetic compatibility Is the panel builder's responsibility.  | 10.9 Insulation properties   |         |   |  |
| 10.9.4 Testing of enclosures made of insulating material  10.10 Temperature rise  10.11 Short-circuit rating  10.12 Electromagnetic compatibility  Does not apply to metal enclosures.  The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.  Is the panel builder's responsibility.  Is the panel builder's responsibility.   | 10.9.2 Power-frequency electric strength                                   |         |   | $U_i = 400 \text{ V AC}$                                     |
| 10.10 Temperature rise  The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.  10.11 Short-circuit rating  Is the panel builder's responsibility.  10.12 Electromagnetic compatibility  Is the panel builder's responsibility.  | 10.9.3 Impulse withstand voltage   |         |   | 2.5 kV   |
| provide heat dissipation data for the devices.  10.11 Short-circuit rating Is the panel builder's responsibility.  10.12 Electromagnetic compatibility Is the panel builder's responsibility.  | 10.9.4 Testing of enclosures made of insulating material                   |         |   | Does not apply to metal enclosures.                          |
| 10.12 Electromagnetic compatibility Is the panel builder's responsibility.   | 10.10 Temperature rise   |         |   |  |
|  | 10.11 Short-circuit rating   |         |   | Is the panel builder's responsibility.                       |
| 10.13 Mechanical function Meets the product standard's requirements.   | 10.12 Electromagnetic compatibility  |         |   | Is the panel builder's responsibility.                       |
|  | 10.13 Mechanical function  |         |   | Meets the product standard's requirements.                   |

## **Technical data ETIM 7.0**

| Distribution | hoards (FG000 | 023) / Cable en | try cabinet (FC | 000268) |
|--------------|---------------|-----------------|-----------------|---------|

Electric engineering, automation, process control engineering / Electrical installation, device / Electrical distribution system (incl. small distribution board) / Cable entry cabinet

| (ecl@ss10.0.1-27-14-24-22 [ADI317007]) |   |     |     |  |
|--|---|-----|-----|--|
| Mounting alongside enclosure           |   |     | No  |  |
| Mounting over enclosure                |   |     | Yes |  |
| Mounting under enclosure               |   |     | Yes |  |
| Number of poles                        |   |     | 4   |  |
| Max. cross section connection cable    | r | mm² | 16  |  |

| Max. cross section incoming cable | mm² | 50    |
|-----------------------------------|-----|-------|
| Connection type                   |     | Clamp |
| Degree of protection (IP)         |     | IP30  |
| Height                            | mm  | 385   |
| Width                             | mm  | 545   |
| Depth                             | mm  | 220   |